

FEATURES

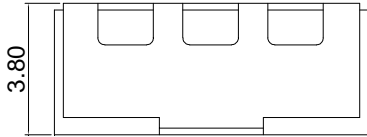
- Small Size,Light weight
- SMT package soldering
- Ideal for Microwave telecommunication

SPECIFICATIONS

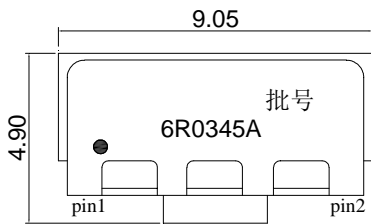
NO.	ITEM	Spec			UNIT	
		Min	Typ	Max		
1	Center Frequency	5935	6530	7125	MHz	
2	Bandwidth [BW]	/	1190	/	MHz	
3	Insertion Loss in BW	/	/	2.8	dB	
4	Ripple in BW	/	/	2.3	dB	
5	VSWR in BW	/	/	2.0	/	
6	Attenuation [Absolute Value]	@30~2500MHz	35	/	/	dB
		@2512~3600MHz	30	/	/	
		@3800~4200MHz	30	/	/	
		@4800~4900MHz	30	/	/	
		@5170~5490MHz	50	/	/	
		@5490~5835MHz	50	/	/	

OUTLINE DRAWING

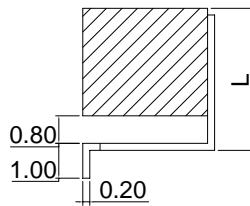
Top View



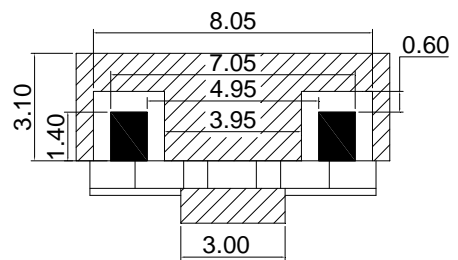
Front View





Side View

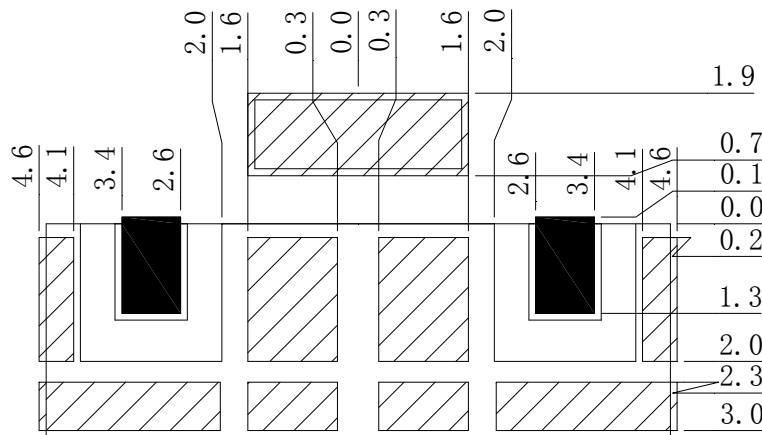


Bottom View



 I/O PORT
 GROUND
 TOLERANCE:0.2 mm(except L)
 L(width)TOLERANCE:±0.3mm

FOOTPRINT



 I/O PORT SOLDERING POINT
 GROUND SOLDERING POINT

ABSOLUTE MAXIMUM RATINGS

Operation Temperature	-40°C to +95°C
Storage Temperature	-40°C to +95°C
Max. Input Power	33dBm

NOTES

- RoHS 2.0/HSF
- Reflow soldering temperature curves

